

PTF 10019

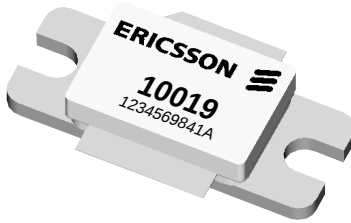
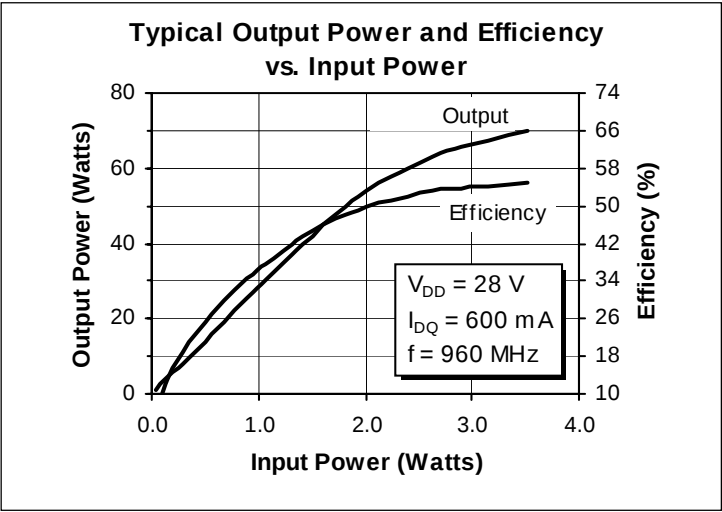
70 Watts, 860–960 MHz

GOLDMOS Field Effect Transistor

Description

The PTF 10019 is an internally matched, 70-watt GOLDMOS FET intended for cellular, GSM and D-AMPS applications from 860 to 960 MHz. This device operates at 50% efficiency with 14.5 dB gain. Nitride surface passivation and full gold metallization ensure excellent device lifetime and reliability.

- **INTERNALLY MATCHED**
- **Performance at 960 MHz, 28 Volts**
 - Output Power = 70 Watts
 - Power Gain = 14.5 dB Typ
 - Efficiency = 50% Typ
- **Full Gold Metallization**
- **Silicon Nitride Passivated**
- **Excellent Thermal Stability**
- **100% Lot Traceability**



Package 20237

RF Specifications (100% Tested)

Characteristic	Symbol	Min	Typ	Max	Units
Gain ($V_{DD} = 28\text{ V}$, $P_{OUT} = 70\text{ W}$, $I_{DQ} = 600\text{ mA}$, $f = 960\text{ MHz}$)	G_{pe}	13.0	14.5	—	dB
Power Output at 1 dB Compression ($V_{DD} = 28\text{ V}$, $I_{DQ} = 600\text{ mA}$, $f = 960\text{ MHz}$)	P-1dB	70	75	—	Watts
Drain Efficiency ($V_{DD} = 28\text{ V}$, $P_{OUT} = 70\text{ W}$, $I_{DQ} = 600\text{ mA}$, $f = 960\text{ MHz}$)	η	45	50	—	%
Load Mismatch Tolerance ($V_{DD} = 28\text{ V}$, $P_{OUT} = 70\text{ W}$, $I_{DQ} = 600\text{ mA}$, $f = 960\text{ MHz}$ —all phase angles at frequency of test)	Y	—	—	10:1	—

All published data at $T_{CASE} = 25^\circ\text{C}$ unless otherwise indicated.

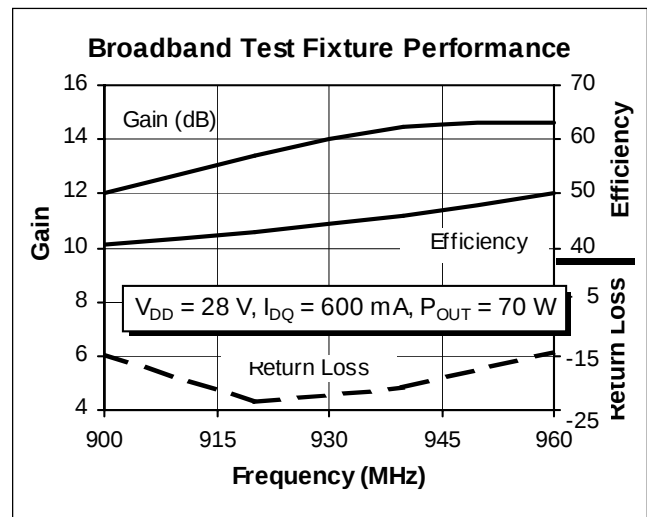
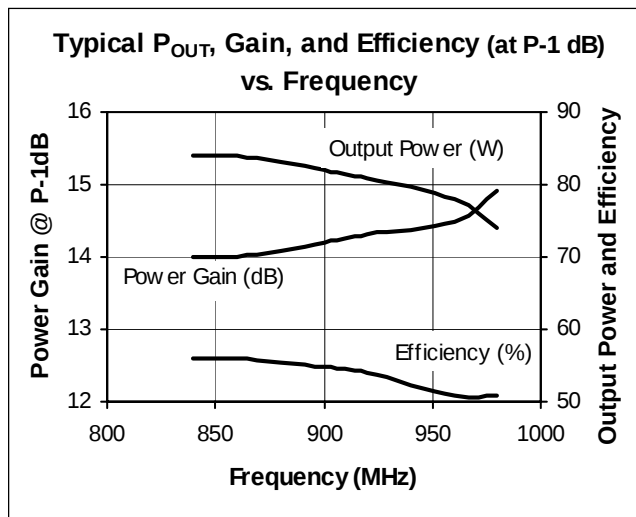
Electrical Characteristics (100% Tested)

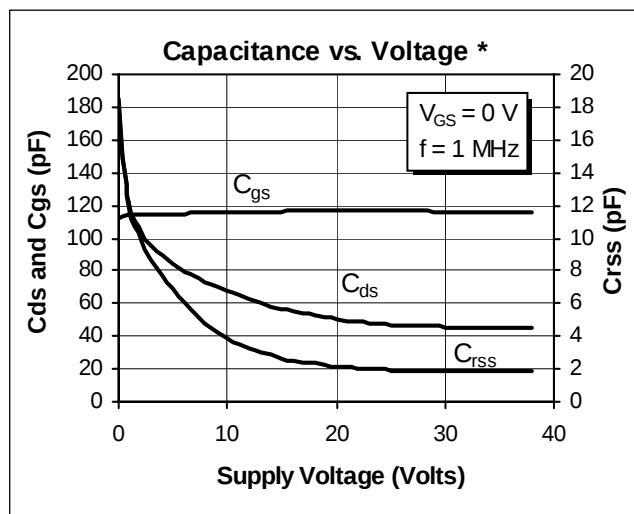
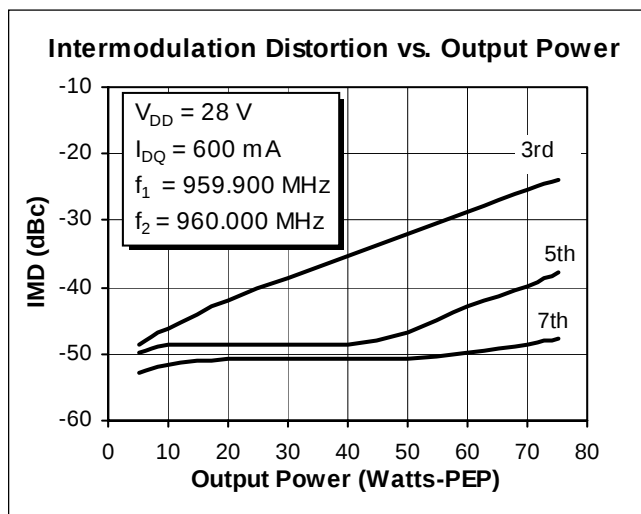
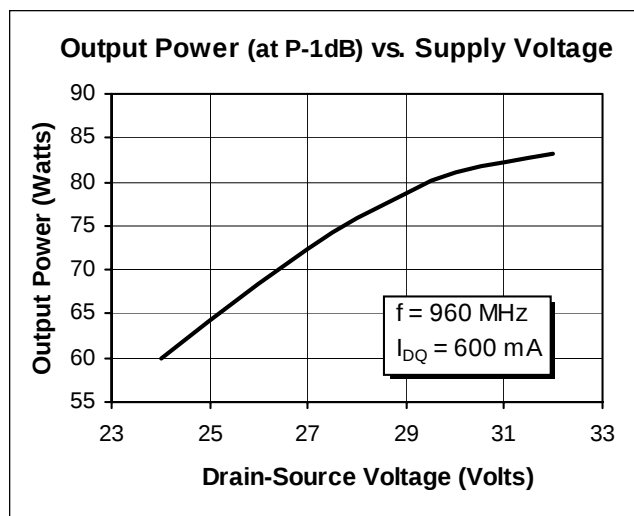
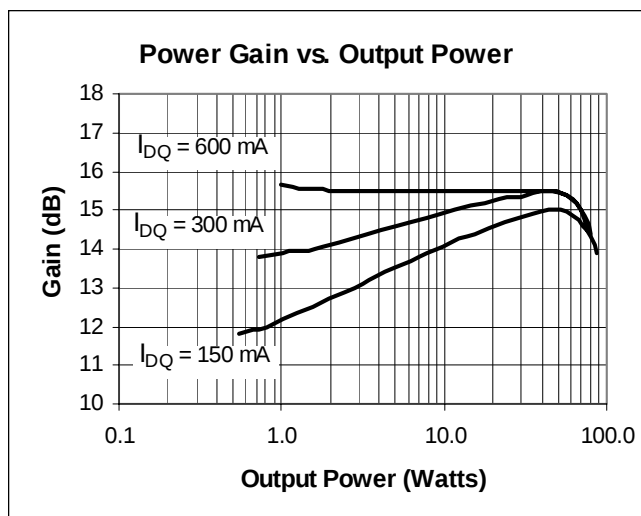
Characteristic	Conditions	Symbol	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$, $I_D = 25\text{ mA}$	$V_{(BR)DSS}$	65	—	—	Volts
Drain-Source Leakage Current	$V_{DS} = 26\text{ V}$, $V_{GS} = 0\text{ V}$	I_{DSS}	—	—	1.0	mA
Gate Threshold Voltage	$V_{DS} = 10\text{ V}$, $I_D = 75\text{ mA}$	$V_{GS(th)}$	3.0	—	5.0	Volts
Forward Transconductance	$V_{DS} = 10\text{ V}$, $I_D = 3\text{ A}$	g_{fs}	—	3.0	—	Siemens

Maximum Ratings

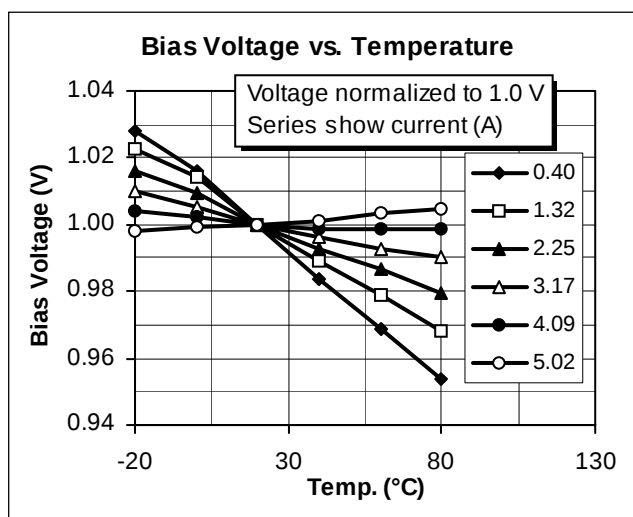
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	65	Vdc
Gate-Source Voltage	V_{GS}	± 20	Vdc
Operating Junction Temperature	T_J	200	$^{\circ}\text{C}$
Total Device Dissipation Above 25°C derate by	P_D	215 1.25	Watts $\text{W}/^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-40 to $+150$	$^{\circ}\text{C}$
Thermal Resistance ($T_{CASE} = 70^{\circ}\text{C}$)	$R_{\theta JC}$	0.8	$^{\circ}\text{C}/\text{W}$

Typical Performance



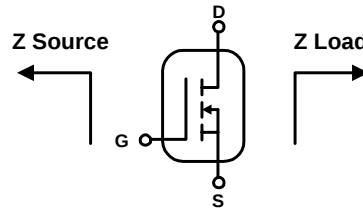


* This part is internally matched. Measurements of the finished product will not yield these figures.

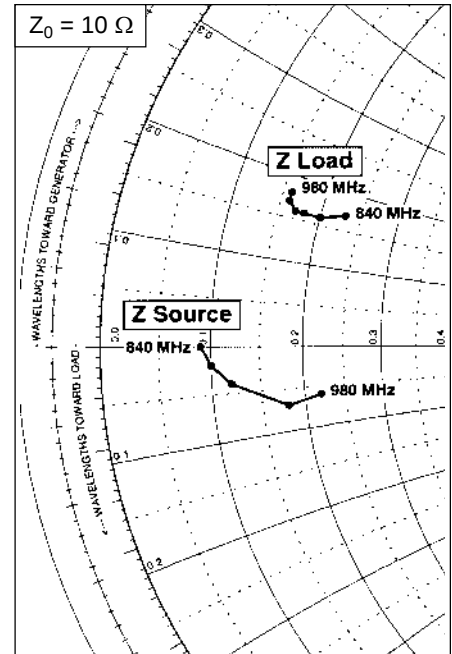


Impedance Data

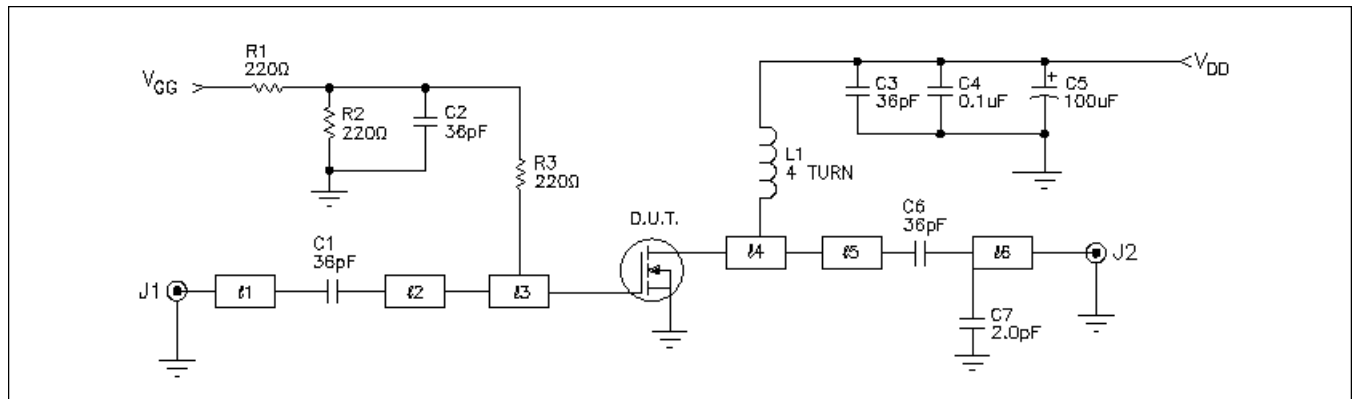
($V_{DD} = 28$ V, $P_{OUT} = 70$ W, $I_{DQ} = 600$ mA)



Frequency MHz	Z Source Ω		Z Load Ω	
	R	jX	R	jX
840	0.9	0	2.3	1.7
860	1.0	-0.2	2.0	1.6
900	1.2	-0.4	1.8	1.6
920	1.2	-0.4	1.7	1.6
960	1.8	-0.7	1.6	1.7
980	2.2	-0.6	1.6	1.8

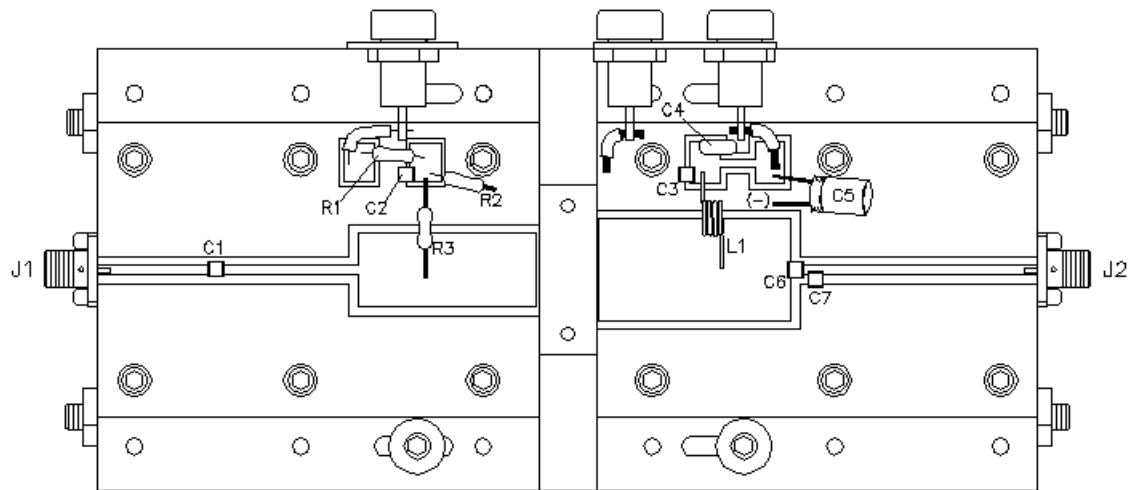


Test Circuit

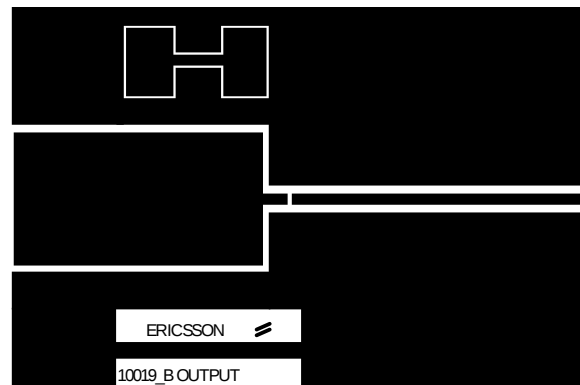
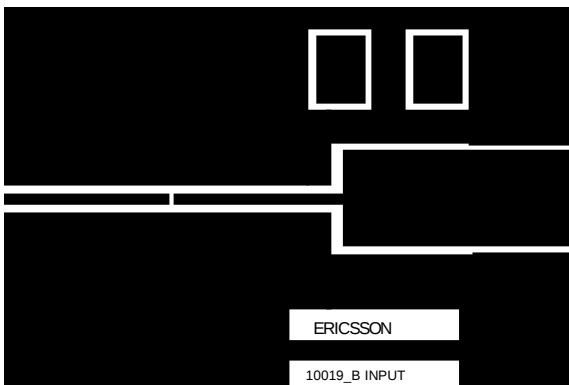


Test Circuit Schematic for $f = 960$ MHz

D.U.T.	PTF 10019	LDMOS FET	C1, C2, C3, C6	36 pF Chip Cap	ATC 100 B 360
l1	0.123 λ 960 MHz	Microstrip 50 Ω	C4	0.1 μ F Capacitor	Digi-Key 4525-ND
l2	0.125 λ 960 MHz	Microstrip 50 Ω	C5	100 μ F, 50 V Electrolytic Capacitor,	Digi-Key P5182-NO
l3	0.186 λ 960 MHz	Microstrip 10 Ω			ATC 100 B 1R7
l4	0.200 λ 960 MHz	Microstrip 7.5 Ω	C7	2.0 pF Chip Cap	ATC 100 B 1R7
l5	0.060 λ 960 MHz	Microstrip 50 Ω	J1, J2	Female SMA Connectors, Panel Mount	
l6	0.217 λ 960 MHz	Microstrip 50 Ω	L1	4 Turn, #20 AWG, .120" I.D.	
			R1, R2, R3	220 Ω , 1/4 W Resistor	Digi-Key 220QBK-ND
			Circuit Board	.031" Thick, $\epsilon_r = 4.0$, 2 oz. copper,	AlliedSignal, G200



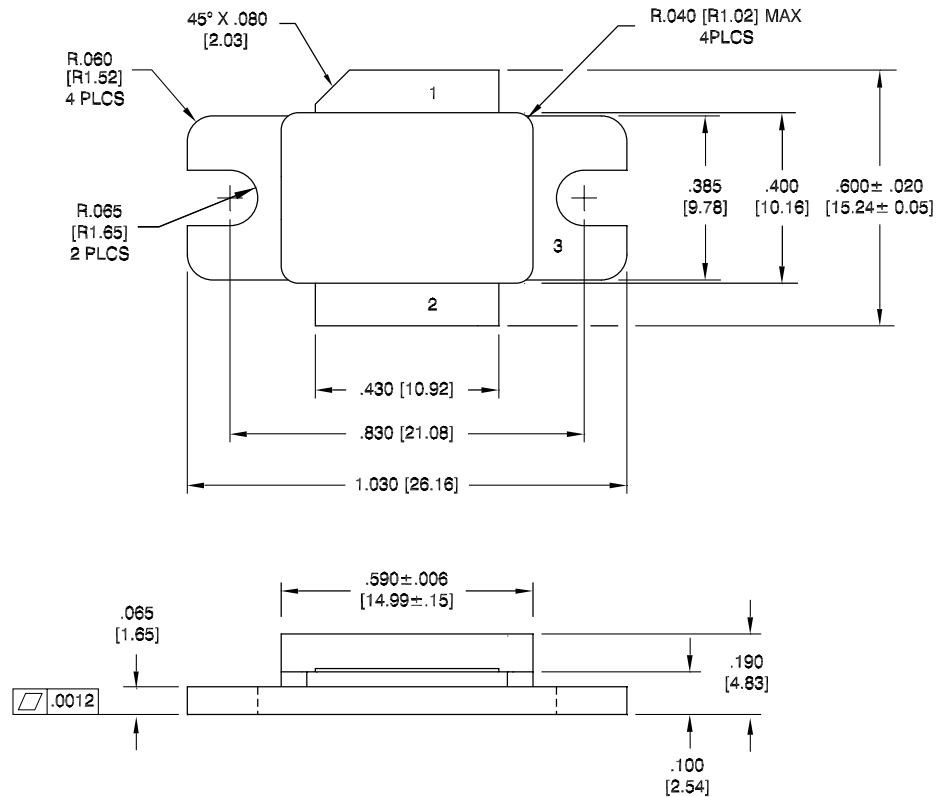
Components Layout (not to scale)



Artwork (not to scale)

Case Outline Specifications

Package 20237



Unless otherwise specified
all tolerances ± 0.005 " [0.13mm]

Pins: 1.Drain 2.Gate 3.Source
Lead Thickness: $0.005 + 0.002/-0.001$ "
[0.13 + 0.05/-0.03mm]

Unless otherwise noted, lids are toleranced with reference to the leads.
Primary dimensions are inches; alternate dimensions are mm.